

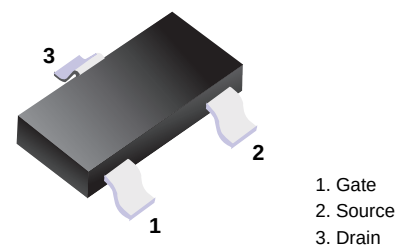
P-Enhancement Field Effect Transistor

Features

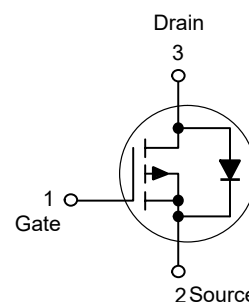
- $V_{DS} = -30V$, $I_D = -4.1A$
 $R_{DS(on)} = 50m\Omega$ (Typ.) @ $V_{GS} = -10V$
- High density cell design for ultra low $R_{DS(on)}$
- Low gate charge

Applications

- Load Switch and in PWM Applications



Simplified outline(SOT-23)



Absolute Maximum Ratings $T_a = 25^\circ C$

Parameter	Symbol	Value	Units
Drain-Source Voltage	$-V_{DS}$	30	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current	$-I_D$	4.1	A
Power Dissipation	P_D	1.4	W
Junction and Storage Temperature Range	T_J, T_{STG}	150, -55 to 150	$^\circ C$
Thermal Characteristics			
Parameter	Symbol	Typ.	Units
Maximum Junction-to-Ambient ^{Note1}	$R_{\theta JA}$	89	$^\circ C/W$

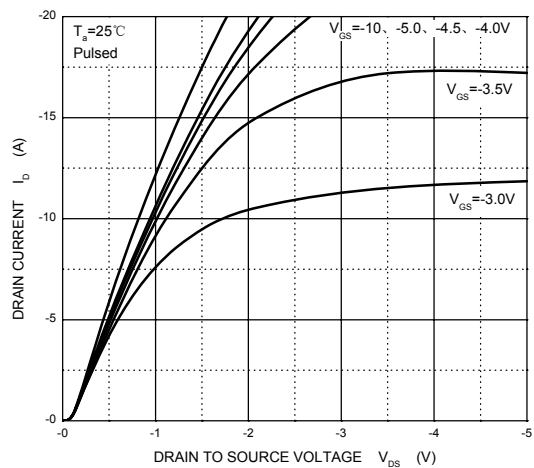
■ Electrical Characteristics Ta = 25°C

Parameter	Symbol	Test Condition	Min	Typ	Max	Units
Static Characteristics						
Drain-source breakdown voltage	$-V_{(BR)DSS}$	$V_{GS} = 0V, I_D = -250\mu A$	30			V
Zero gate voltage drain current	$-I_{DSS}$	$V_{DS} = -24V, V_{GS} = 0V$			1	μA
Gate-source leakage current	I_{GSS}	$V_{GS} = \pm 20V, V_{DS} = 0V$			± 100	nA
Drain-source on-resistance ^{Note2}	$R_{DS(on)}$	$V_{GS} = -10V, I_D = -4.1A$		50	60	m Ω
		$V_{GS} = -4.5V, I_D = -3A$		68	87	m Ω
Gate threshold voltage ^{Note2}	$-V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = -250\mu A$	1	1.4	3	V
Forward tranconductance ^{Note2}	g_{FS}	$V_{DS} = -5V, I_D = -4A$	5.5			S
Dynamic Characteristics						
Input capacitance	C_{iss}	$V_{DS} = -15V, V_{GS} = 0V, f = 1MHz$		700		pF
Output capacitance	C_{oss}			120		pF
Reverse transfer capacitance	C_{rss}			75		pF
Switching Characteristics						
Turn-on delay time	$t_{d(on)}$	$V_{GS} = -10V, V_{DS} = -15V,$ $R_L = 3.6\Omega, R_{GEN} = 3\Omega$		8.6		ns
Turn-on rise time	t_r			5.0		ns
Turn-off delay time	$t_{d(off)}$			28.2		ns
Turn-off fall time	t_f			13.5		ns
Source-Drain Diode Characteristics						
Diode forward voltage	V_{SD}	$I_S = -1A, V_{GS} = 0V$			-1	V

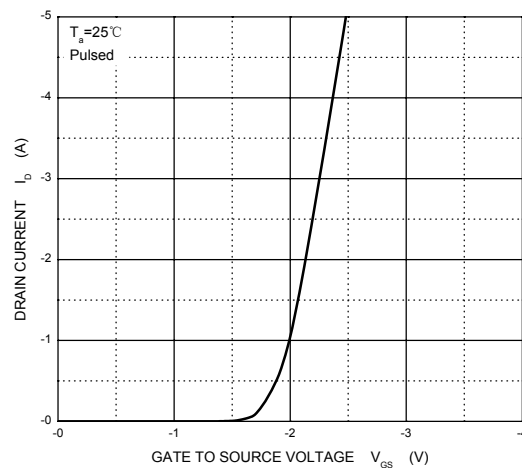
Notes:

1. The value of $R_{\theta JA}$ is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with $T_A = 25^\circ C$. The value in any given application depends on the user's specific board design.
2. Pulse test: Pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$.

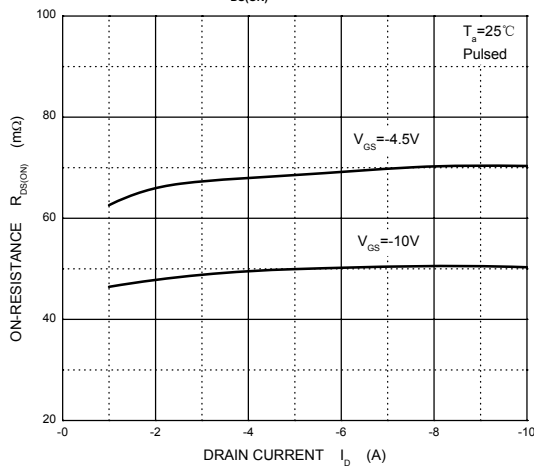
Output Characteristics



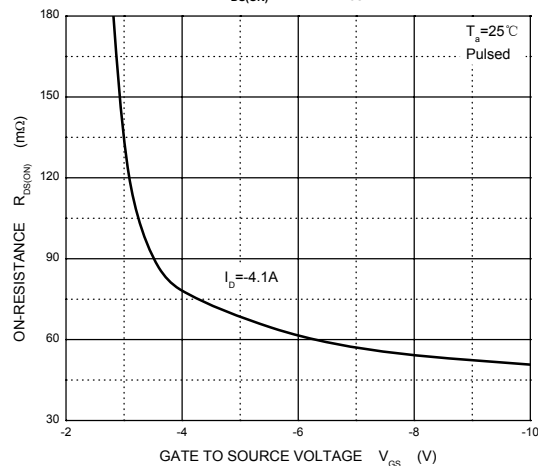
Transfer Characteristics



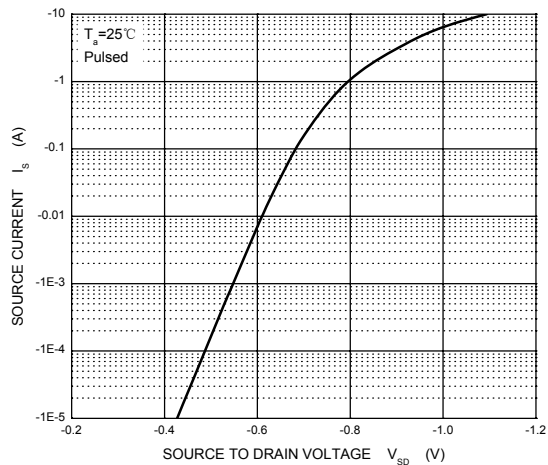
$R_{DS(ON)}$ — I_D



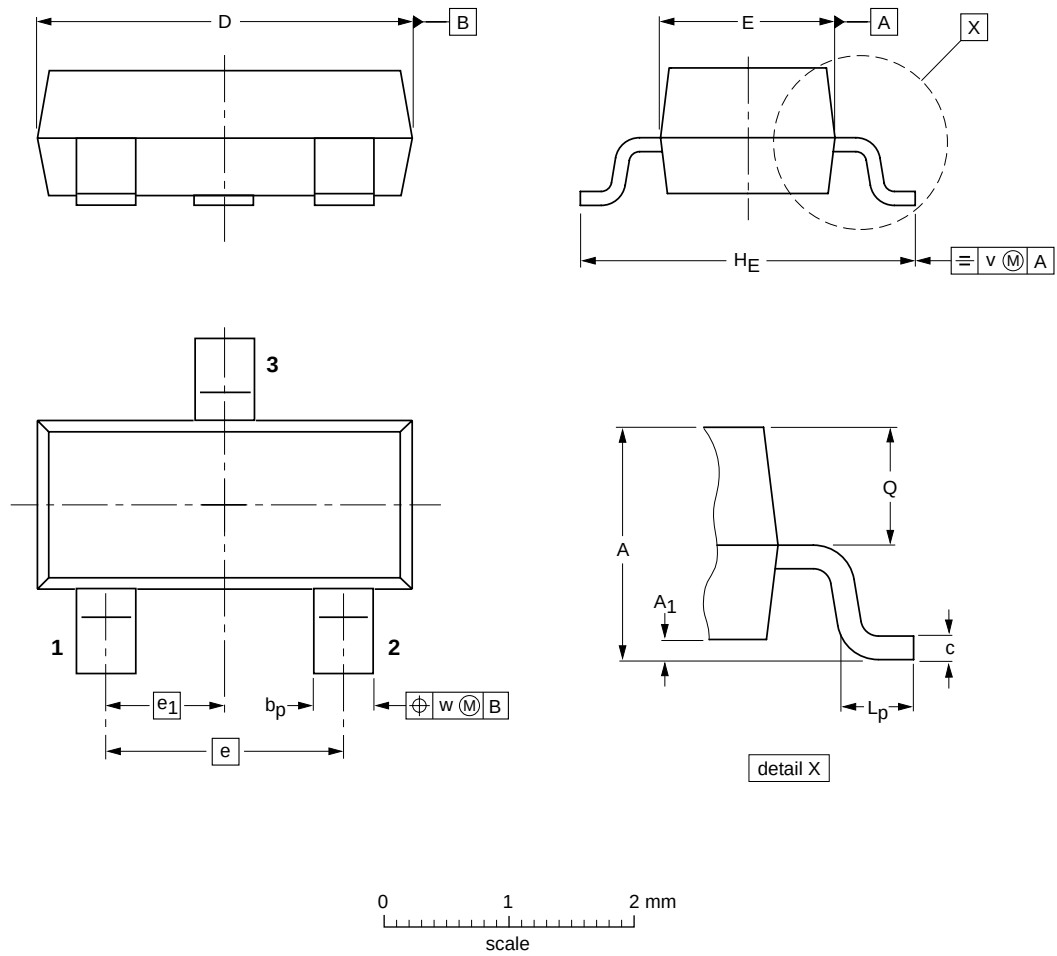
$R_{DS(ON)}$ — V_{GS}



I_S — V_{SD}



■ SOT-23



DIMENSIONS (mm are the original dimensions)

UNIT	A	A ₁ max.	b _p	c	D	E	e	e ₁	H _E	L _p	Q	v	w
mm	1.1 0.9	0.1	0.48 0.38	0.15 0.09	3.0 2.8	1.4 1.2	1.9	0.95	2.5 2.1	0.45 0.15	0.55 0.45	0.2	0.1